



## SSC8L38GT8

### N-Channel Enhancement Mode MOSFET

#### ➤ Features

$V_{DS}$	$V_{GS}$	$R_{DS(ON)}$	$I_D$
30V	$\pm 20V$	2.6m $\Omega$ @10V	125A
		4.5m $\Omega$ @4V5	

#### ➤ Description

This device is N-Channel enhancement MOSFET. Uses SGT technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

**100% UIS +  $\Delta V_{DS}$  +  $R_g$  Tested!**

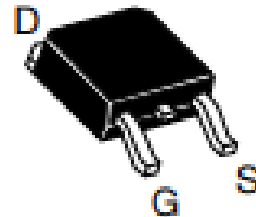
#### ➤ Applications

- Load Switch
- Portable Devices
- DCDC Conversion
- Power Supplies
- Synchronous Rectification

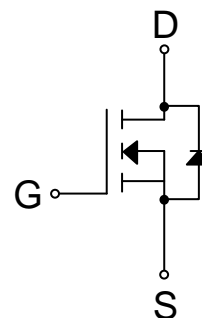
#### ➤ Ordering Information

Device	Package	Shipping
SSC8L38GT8	TO-252-2L	2500/Reel

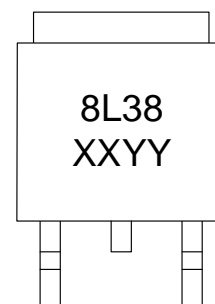
#### ➤ Pin Configuration



**TO-252-2L (Top View)**



**Pin Configuration**



**Marking**

(XXYY: Internal Traceability Code)

**➤ Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{\text{DSS}}$	Drain-to-Source Voltage	30	V
$V_{\text{GSS}}$	Gate-to-Source Voltage	$\pm 20$	V
$I_{\text{D}}$	Continuous Drain Current <sup>d</sup>	$T_{\text{C}}=25^{\circ}\text{C}$	A
		$T_{\text{C}}=100^{\circ}\text{C}$	
$I_{\text{DSM}}$	Continuous Drain Current <sup>a</sup>	$T_{\text{A}}=25^{\circ}\text{C}$	A
		$T_{\text{A}}=70^{\circ}\text{C}$	
$I_{\text{DM}}$	Pulsed Drain Current <sup>b</sup>	500	A
$P_{\text{D}}$	Power Dissipation <sup>c</sup>	$T_{\text{C}}=25^{\circ}\text{C}$	W
		$T_{\text{C}}=100^{\circ}\text{C}$	
$P_{\text{DSM}}$	Power Dissipation <sup>a</sup>	$T_{\text{A}}=25^{\circ}\text{C}$	W
		$T_{\text{A}}=70^{\circ}\text{C}$	
$I_{\text{AS}}$	Avalanche Current <sup>b</sup> $L=0.5\text{mH}$ Single Pulse	35	A
$E_{\text{AS}}$	Avalanche Energy <sup>b</sup> $L=0.5\text{mH}$ Single Pulse	260	mJ
$T_{\text{J}}$	Operation junction temperature	-55~150	$^{\circ}\text{C}$
$T_{\text{STG}}$	Storage temperature range	-55~150	

**➤ Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$R_{\theta\text{JA}}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	30	$^{\circ}\text{C}/\text{W}$
$R_{\theta\text{JC}}$	Junction-to-Case Thermal Resistance	2	

Note:

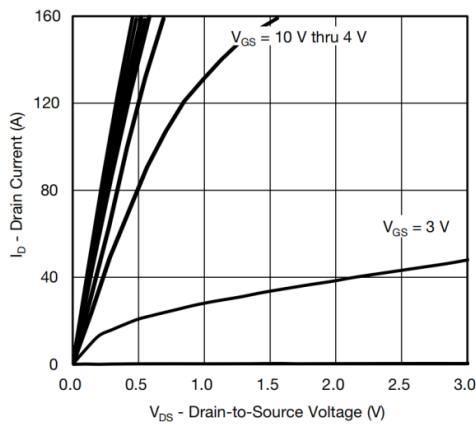
- The value of  $R_{\theta\text{JA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_{\text{A}}=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_{\text{D}}$  is based on  $T_{\text{J(MAX)}}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- The maximum current rating is package limited.

**➤ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

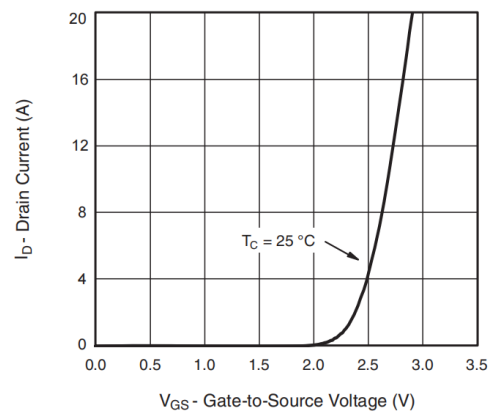
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1.3	1.8	2.3	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 30A		2.6	3.6	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 20A		4.5	6	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 20A		30		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 20A		0.8	1.4	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		1.1		Ω
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1MHz		1850		pF
Output Capacitance	C <sub>OSS</sub>			1124		
Reverse Transfer Capacitance	C <sub>RSS</sub>			102		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 30A		17		nC
Gate to Source Charge	Q <sub>GS</sub>			7.6		
Gate to Drain Charge	Q <sub>GD</sub>			5.5		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 4.5V, V <sub>DS</sub> = 20V, R <sub>L</sub> = 1Ω, R <sub>G</sub> = 3Ω,		20		ns
Rise Time	T <sub>r</sub>			41		
Turn-off Delay Time	T <sub>D(OFF)</sub>			22		
Fall Time	T <sub>f</sub>			19		
Diode Recovery Time	T <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		43		ns
Diode Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =20A, di/dt=100A/us		29		nC



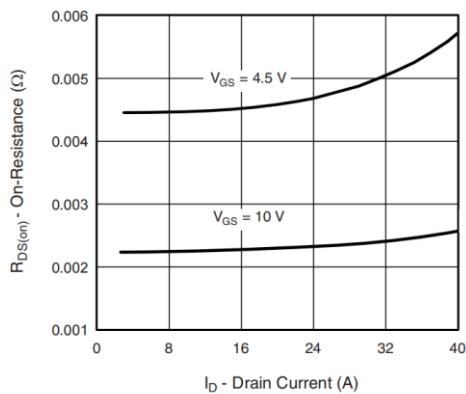
➤ **Typical Performance Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)**



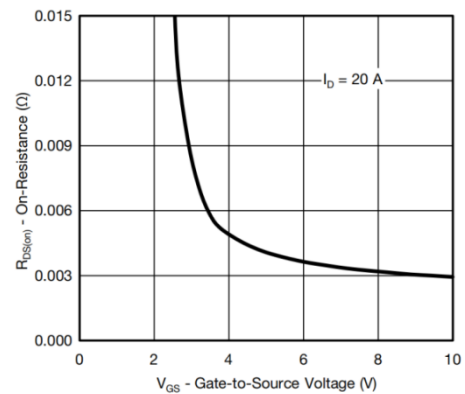
**Output Characteristics**



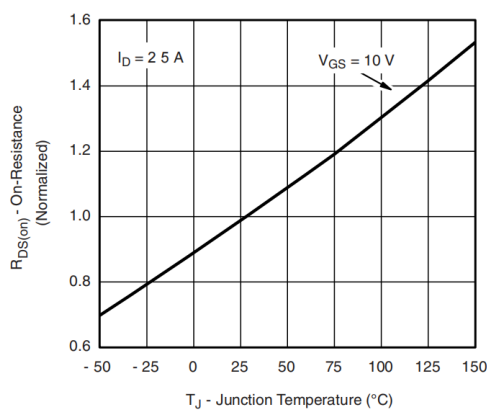
**Transfer Characteristics**



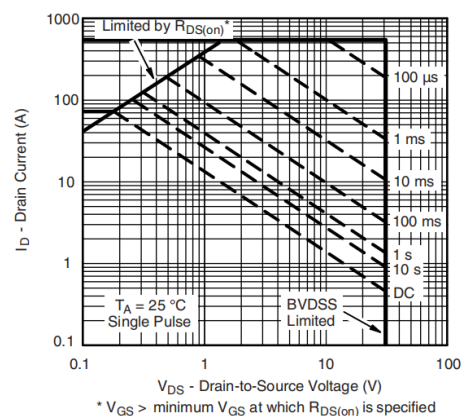
**On-Resistance vs. Drain Current and Gate Voltage**



**On-Resistance vs. Gate-to-Source Voltage**

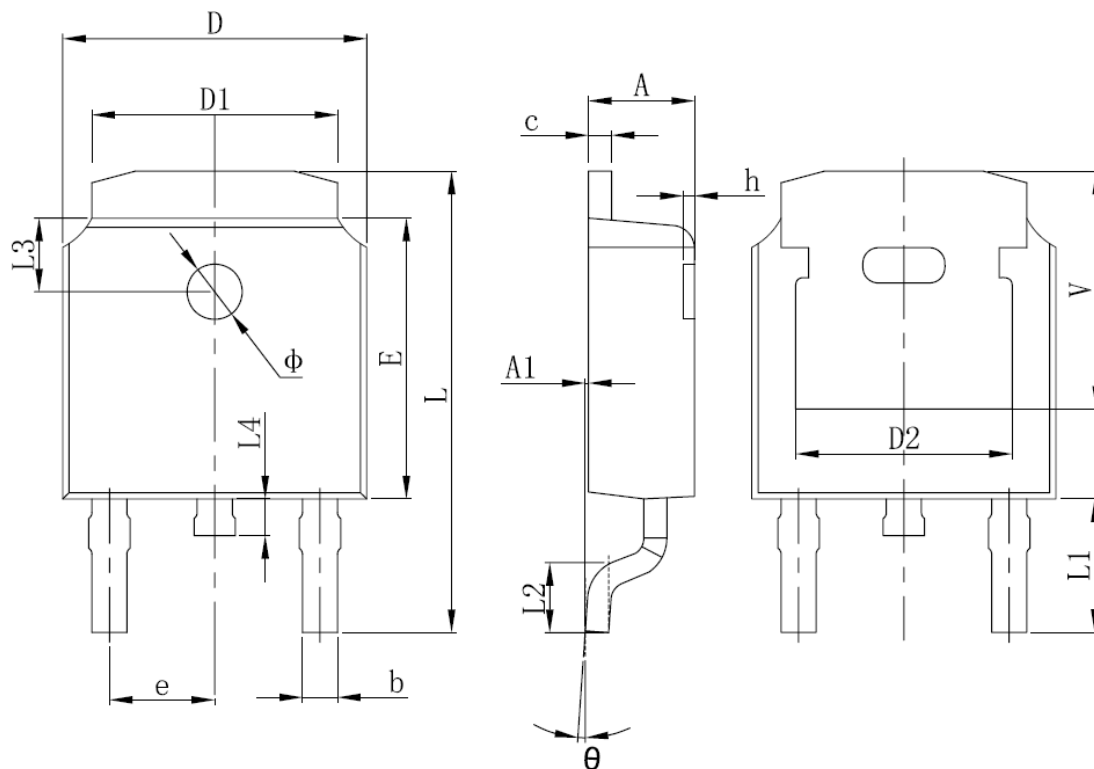


**On-Resistance vs. Junction Temperature**



**Safe Operating Area, Junction-to-Ambient**

## ➤ Package Information



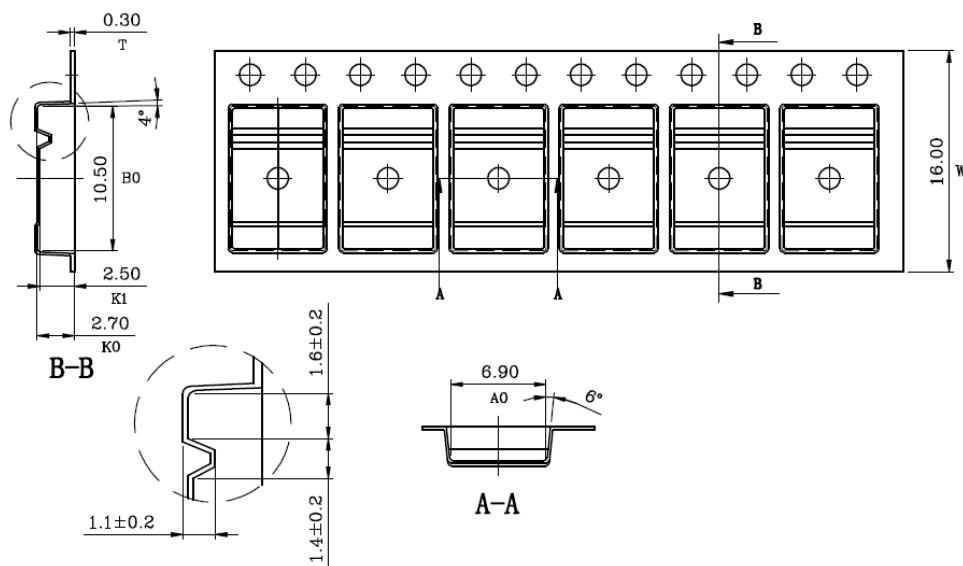
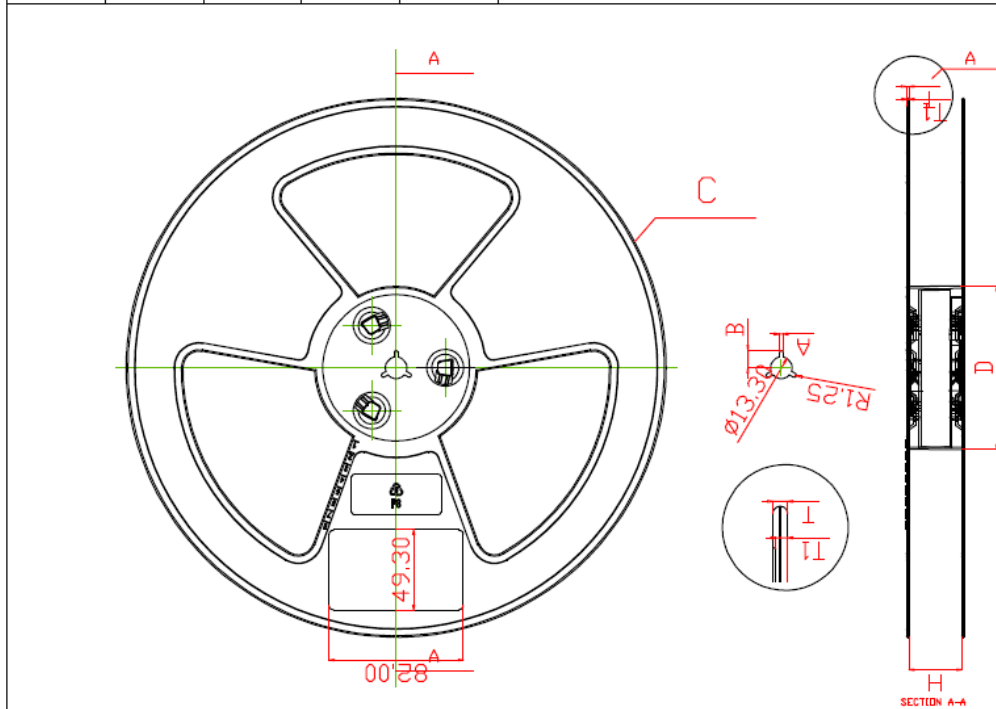
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

## ➤ Tape and Reel

材质: PS

未标注公差:  $\pm 0.2$

H	12	16	24	32
C $\pm 0.2$	330	330	330	330
T1 $\pm 0.2$	1.45	1.45	1.45	1.45
B $\pm 0.2$	10.7	10.7	10.7	10.7
A $\pm 0.2$	2.5	2.5	2.5	2.5
T $\pm 0.2$	1.85	1.85	1.85	1.85
D $\pm 0.2$	100	100	100	100



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